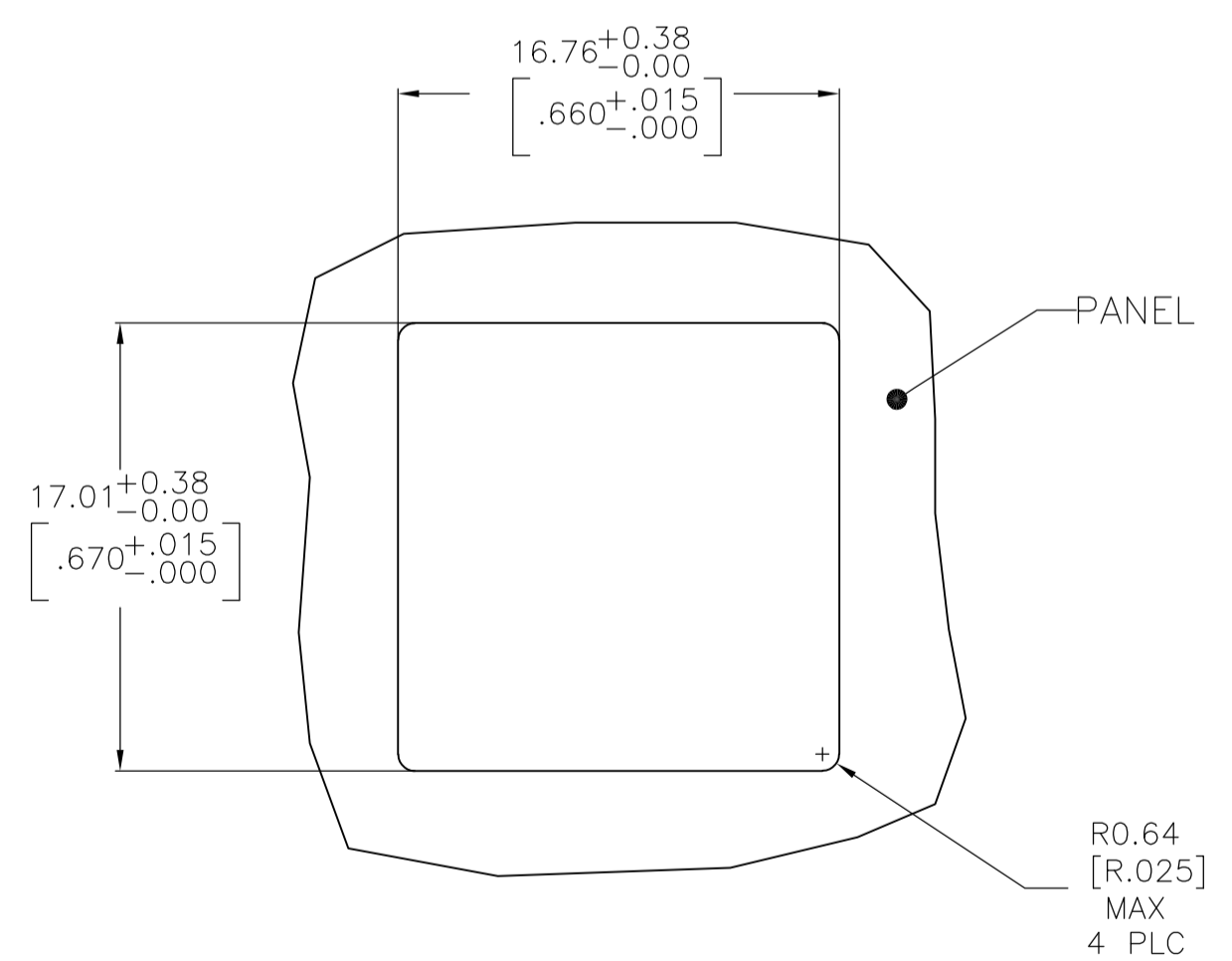


RECOMMENDED PRINTED
CIRCUIT BOARD LAYOUT
COMPONENT SIDE SHOWN



RECOMMENDED PANEL
CUTOUT

- MATERIAL:
HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27 μ m[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81 μ m[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0 μ m [.000120] MIN THICK REFLOWED TIN.

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

2.79-3.30 [.120±.010]	5557969-2
2.79-3.56 [.125±.015]	5557969-1
DIM A	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN A FERNANDEZ-DOCKS 06JUN2005		STE TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 06JUN2005		APVD S. FLICKINGER 06JUN2005	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME		MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL	
0 PLC ± -		PRODUCT SPEC		108-1163	
1 PLC ± -		APPLICATION SPEC		114-2048	
2 PLC ± 0.13[.005]		SIZE		A1	
3 PLC ± -		CASE CODE		00779	
4 PLC ± -		DRAWING NO		5557969	
ANGLES ± -		WEIGHT		-	
MATERIAL SEE NOTE 1		FINISH SEE NOTE 1		CUSTOMER DRAWING	
		SCALE		4:1	
		SHEET		1 OF 1	
		REV		D1	